

L Number	Hits	Search Text	DB	Time stamp
1	159222	(electrode or wir\$3) with (plat\$3 or coat\$3)	USPAT	2004/05/26 13:47
2	88860	(electrode) with (plat\$3 or coat\$3)	USPAT	2004/05/26 13:47
3	25278	(electrode) near (plat\$3 or coat\$3)	USPAT	2004/05/26 13:59
4	2165	((electrode) near (plat\$3 or coat\$3)) and (protect\$3) near (layer or film)	USPAT	2004/05/26 13:49
5	655	((electrode) near (plat\$3 or coat\$3)) and (protect\$3) near (layer or film)) and 257/\$.ccls.	USPAT	2004/05/26 15:41
6	0	(electrode) near (plat\$3 or coat\$3) with electrode near (upper-side or upper near side) near surfaces	USPAT	2004/05/26 14:00
7	18	(electrode) near (plat\$3 or coat\$3) with (upper-side or upper near side) near surfaces	USPAT	2004/05/26 14:05
8	3664	(electrode) near (plat\$3 or coat\$3) with (gap or spac\$3)	USPAT	2004/05/26 14:06
9	166	(electrode) near (plat\$3 or coat\$3) with (gap or spac\$3) with (protect\$3 or insulat\$3) near (film or layer)	USPAT	2004/05/26 14:16
10	895	(electrode) near (plat\$3 or coat\$3) with (gap or spac\$3) with surface	USPAT	2004/05/26 15:10
14	897	174/257	USPAT	2004/05/26 15:41
15	1002	174/257	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 15:55
16	3095	174/260	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 17:06
17	2218	174/260 and (bumps or balls or electrodes or pads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 15:56
18	2010	174/260 and (bumps or balls or pads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 15:56
19	1403	174/260 and (bumps or balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 16:29
20	1	"6448649"	USPAT	2004/05/26 16:01
21	1692	174/260 not (174/260 and (bumps or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 16:31
22	1		USPAT	2004/05/26 16:33
23	1		USPAT	2004/05/26 16:33
24	1		USPAT	2004/05/26 16:34
25	1		USPAT	2004/05/26 16:34
26	1		USPAT	2004/05/26 16:34
27	1		USPAT	2004/05/26 16:34
28	1		USPAT	2004/05/26 16:34
29	1		USPAT	2004/05/26 16:35
30	1		USPAT	2004/05/26 16:35
31	1		USPAT	2004/05/26 16:35
32	1		USPAT	2004/05/26 16:35
33	1		USPAT	2004/05/26 16:35
34	1		USPAT	2004/05/26 16:35
35	1		USPAT	2004/05/26 16:35
36	1		USPAT	2004/05/26 16:36
37	1		USPAT	2004/05/26 16:39
38	1		USPAT	2004/05/26 16:39

39	1		USPAT	2004/05/26 16:39
40	1		USPAT	2004/05/26 16:40
41	1		USPAT	2004/05/26 16:40
42	1647	361/767	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 17:27
43	594	361/768	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 17:46
44	1386	361/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 18:10
45	2062	228/180.22	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 18:10
46	1811	228/180.22 and (pad or ball or bumps)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 18:12
-	490	(pad or contact\$2 or terminat\$2 or eletrode) with trapezoid	USPAT	2004/05/26 13:43
-	2456	(pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT	2004/05/15 19:42
-	490	(pad or contact\$2 or terminat\$2) with trapezoid	USPAT	2004/05/15 15:41
-	1	"08241940"	JPO	2004/05/15 19:42
-	13	6228466.pn. or 6573598.pn. or 6310304.pn. or 6310364.pn. or 6583445.pn. or 6653218.pn. or 6528874.pn. or 6495916.pn. or 6579739.pn. or 5388577.pn. or 6387793.pn. or 6228466.pn. or 6198169.pn. or 6104201.pn.	USPAT; JPO	2004/05/15 16:04
-	14	6228466.pn. or 6573598.pn. or 6310304.pn. or 6310364.pn. or 6583445.pn. or 6653218.pn. or 6528874.pn. or 6495916.pn. or 6579739.pn. or 5388577.pn. or 6387793.pn. or 6228466.pn. or 6198169.pn. or 6104201.pn. or 5609704.pn.	USPAT; JPO	2004/05/15 16:04
-	2	((pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3) and (semiconductor or die or chip or IC)) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3 same (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:19
-	632	((pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3) and (semiconductor or die or chip or IC)	USPAT	2004/05/15 16:11
-	1	"5639685".PN.	USPAT	2004/05/15 16:13
-	1	"5877052".PN.	USPAT	2004/05/15 16:13
-	1	"5913119".PN.	USPAT	2004/05/15 16:13
-	73	257/779 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:50
-	100	257/780 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:48
-	68	(257/780 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)) not (257/779 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film))	USPAT	2004/05/15 16:44

-	4817	(semiconductor or die or chip or IC) and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:49
-	23	(semiconductor or die or chip or IC) and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film) with upper near portion 257/779	USPAT	2004/05/17 10:40
-	1261	(257/737 or 257/738) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT	2004/05/15 16:51
-	34	(257/739 or 257/778) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:49
-	20	(257/779 or 257/780) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:50
-	21	(257/781 or 257/782) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:51
-	13	(257/783 or 257/784) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:51
-	26	(257/785 or 257/786) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:51
-	24	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) and soder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:52
-	1	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) and soder	USPAT	2004/05/17 10:41
-	581	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3)	USPAT	2004/05/17 11:55
-	388577	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") saame (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3)	USPAT	2004/05/17 11:55
-	7864	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") same (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3)	USPAT	2004/05/17 11:58
-	3161	((semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") same (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3)) and 257/\$.ccls.	USPAT	2004/05/17 11:57
-	697	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") same (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (film or layer)	USPAT	2004/05/17 12:08
-	99	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (bump) with (coat\$3 or plat\$3)	USPAT	2004/05/17 12:17
-	200	(semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (bump) and bump with (coat\$3 or plat\$3)	USPAT	2004/05/17 12:18

-	101	((semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (bump) and bump with (coat\$3 or plat\$3)) not ((semiconductor or die or chip or IC) and ("Cu" or copper or silver or "Ag") near (bump) with (coat\$3 or plat\$3))	USPAT	2004/05/17 12:30
-	1	"5442240".PN.	USPAT	2004/05/17 12:20
-	1	"5874780".PN.	USPAT	2004/05/17 12:20
-	1	"5892271".PN.	USPAT	2004/05/17 12:21
-	1	"6137183".PN.	USPAT	2004/05/17 12:21
-	1	"6137184".PN.	USPAT	2004/05/17 12:21
-	1	"6153938".PN.	USPAT	2004/05/17 12:21
-	1	"6177730".PN.	USPAT	2004/05/17 12:22
-	0	5609704.pn. with (gold or "Au")	USPAT	2004/05/17 12:30
-	1	5609704.pn. and (gold or "Au")	USPAT	2004/05/17 12:30